74AHC08; 74AHCT08

Quad 2-input AND gate Rev. 03 — 14 November 2007

Product data sheet

General description 1.

The 74AHC08; 74AHCT08 is a high-speed Si-gate CMOS device and is pin compatible with Low-power Schottky TTL (LSTTL). They are specified in compliance with JEDEC standard JESD7-A.

The 74AHC08; 74AHCT08 provides the quad 2-input AND function.

2. **Features**

- Balanced propagation delays
- All inputs have a Schmitt-trigger action
- Inputs accepts voltages higher than V_{CC}
- For 74AHC08 only: operates with CMOS input levels
- For 74AHCT08 only: operates with TTL input levels
- ESD protection:
 - ◆ HBM JESD22-A114E exceeds 2000 V
 - MM JESD22-A115-A exceeds 200 V
 - CDM JESD22-C101C exceeds 1000 V
- Multiple package options
- Specified from -40 °C to +85 °C and from -40 °C to +125 °C

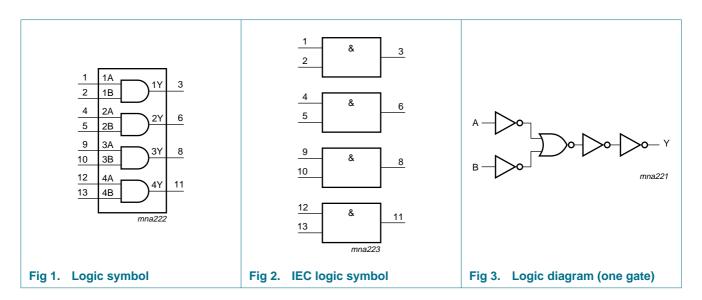
Ordering information 3.

Table 1. **Ordering information**

Type number	Package											
	Temperature range	Name	Description	Version								
74AHC08D	–40 °C to +125 °C	SO14	plastic small outline package; 14 leads;	SOT108-1								
74AHCT08D			body width 3.9 mm									
74AHC08PW	–40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads;	SOT402-1								
74AHCT08PW			body width 4.4 mm									
74AHC08BQ	–40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very	SOT762-1								
74AHCT08BQ			thin quad flat package; no leads; 14 terminals; body $2.5 \times 3 \times 0.85$ mm									

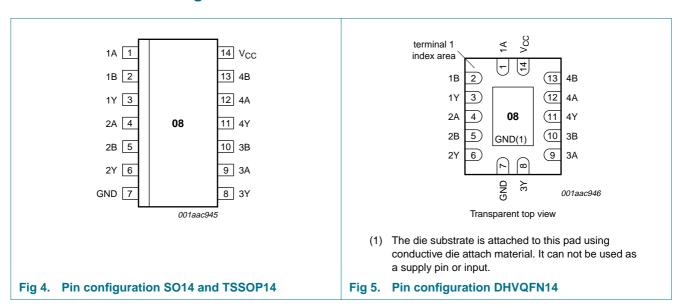


4. Functional diagram



5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

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Symbol	Pin	Description
1A	1	data input
1B	2	data input
1Y	3	data output
2A	4	data input
2B	5	data input
2Y	6	data output
GND	7	ground (0 V)
3Y	8	data output
3A	9	data input
3B	10	data input
4Y	11	data output
4A	12	data input
4B	13	data input
V_{CC}	14	supply voltage

6. Functional description

Table 3. Function selection[1]

Input		Output
nA	nB	nY
L	X	L
X	L	L
Н	Н	Н

^[1] H = HIGH voltage level; L = LOW voltage level; X = don't care

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+7.0	V
VI	input voltage		-0.5	+7.0	V
I _{IK}	input clamping current	$V_1 < -0.5 V$	<u>[1]</u> –20	-	mA
I _{OK}	output clamping current	$V_O < -0.5 \text{ V or } V_O > V_{CC} + 0.5 \text{ V}$	[1] _	±20	mA
Io	output current	$V_{O} = -0.5 \text{ V to } (V_{CC} + 0.5 \text{ V})$	-	±25	mA
I _{CC}	supply current		-	75	mA
I_{GND}	ground current		–75	-	mA
T _{stg}	storage temperature		-65	+150	°C

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Table 4. Limiting values ...continued

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
P _{tot}	total power dissipation	$T_{amb} = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}$			
	SO14 package		<u>[2]</u> -	500	mW
	TSSOP14 package		<u>[3]</u> -	500	mW
	DHVQFN14 package		<u>[4]</u> _	500	mW

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- [2] P_{tot} derates linearly with 8 mW/K above 70 °C.
- [3] P_{tot} derates linearly with 5.5 mW/K above 60 °C.
- [4] Ptot derates linearly with 4.5 mW/K above 60 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	74AH	C08		74AH0	74AHCT08			
			Min	Тур	Max	Min	Тур	Max		
V_{CC}	supply voltage		2.0	5.0	5.5	4.5	5.0	5.5	V	
V_{I}	input voltage	0	-	5.5	0	-	5.5	V		
Vo	output voltage		0	-	V_{CC}	0	-	V_{CC}	V	
T _{amb}	ambient temperature		-40	+25	+125	-40	+25	+125	°C	
Δt/ΔV	input transition rise and fall rate	V_{CC} = 3.3 V \pm 0.3 V	-	-	100	-	-	-	ns/V	
		$V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	-	-	20	-	-	20	ns/V	

9. Static characteristics

Table 6. Static characteristics

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		25 °C		-40 °C 1	to +85 °C	–40 °C t	o +125 °C	Unit
			Min	Тур	Max	Min	Max	Min	Max	
For type	74AHC08					•				
V _{IH} HIGH-level		V _{CC} = 2.0 V	1.5	-	-	1.5	-	1.5	-	V
	input voltage	V _{CC} = 3.0 V	2.1	-	-	2.1	-	2.1	-	V
		V _{CC} = 5.5 V	3.85	-	-	3.85	-	3.85	-	V
V _{IL} LOW-level		V _{CC} = 2.0 V	-	-	0.5	-	0.5	-	0.5	V
	input voltage	V _{CC} = 3.0 V	-	-	0.9	-	0.9	-	0.9	V
		V _{CC} = 5.5 V	-	-	1.65	-	1.65	-	1.65	V
V_{OH}	HIGH-level	$V_I = V_{IH}$ or V_{IL}								
	output voltage	$I_O = -50 \mu A$; $V_{CC} = 2.0 \text{ V}$	1.9	2.0	-	1.9	-	1.9	-	V
		$I_O = -50 \mu A$; $V_{CC} = 3.0 \text{ V}$	2.9	3.0	-	2.9	-	2.9	-	V
		$I_O = -50 \mu A$; $V_{CC} = 4.5 \text{ V}$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_{O} = -4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.58	-	-	2.48	-	2.4	-	V
		$I_{O} = -8.0 \text{ mA}; V_{CC} = 4.5 \text{ V}$	3.94	-	-	3.8	-	3.7	-	V

Table 6. Static characteristics ...continued Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		25 °C		-40 °C 1	to +85 °C	-40 °C t	Unit	
			Min	Тур	Max	Min	Max	Min	Max	
V _{OL}	LOW-level	$V_I = V_{IH}$ or V_{IL}								
	output voltage	$I_O = 50 \mu A; V_{CC} = 2.0 \text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 50 \mu A; V_{CC} = 3.0 \text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 50 \mu A; V_{CC} = 4.5 V$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.36	-	0.44	-	0.55	V
		$I_O = 8.0 \text{ mA}; V_{CC} = 4.5 \text{ V}$	-	-	0.36	-	0.44	-	0.55	V
I _I	input leakage current	V_I = 5.5 V or GND; V_{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μΑ
I _{CC}	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 5.5 \text{ V}$	-	-	2.0	-	20	-	40	μΑ
Cı	input capacitance		-	3.0	10	-	10	-	10	pF
For type	74AHCT08									
V_{IH}	HIGH-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	2.0	-	-	2.0	-	2.0	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	-	-	8.0	-	0.8	-	0.8	V
V_{OH}	HIGH-level	$V_I = V_{IH}$ or V_{IL} ; $V_{CC} = 4.5 \text{ V}$								
	output voltage	$I_{O} = -50 \mu A$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_{O} = -8.0 \text{ mA}$	3.94	-	-	3.8	-	3.7	-	V
V_{OL}	LOW-level	$V_I = V_{IH}$ or V_{IL} ; $V_{CC} = 4.5 \text{ V}$								
	output voltage	$I_O = 50 \mu A$	-	0	0.1	-	0.1	-	0.1	V
		$I_0 = 8.0 \text{ mA}$	-	-	0.36	-	0.44	-	0.55	V
l _l	input leakage current	V_I = 5.5 V or GND; V_{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μΑ
I _{CC}	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 5.5 \text{ V}$	-	-	2.0	-	20	-	40	μΑ
Δl _{CC}	additional supply current	per input pin; $V_{I} = V_{CC} - 2.1 \text{ V}; I_{O} = 0 \text{ A};$ other pins at V_{CC} or GND; $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	-	-	1.35	-	1.5	-	1.5	mA
Cı	input capacitance		-	3.0	10	-	10	-	10	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics

GND = 0 V; For test circuit see Figure 7.

Symbol	Parameter	Conditions			25 °C		-40 °C	to +85 °C	-40 °C t	o +125 °C	Unit
				Min	Typ[1]	Max	Min	Max	Min	Max	1
For type	74AHC08										
t _{pd}	propagation	nA, nB to nY; see Figure 6	[2]								
	delay	$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$									
		C _L = 15 pF		-	4.0	8.8	1.0	10.5	1.0	11.0	ns
		$C_L = 50 pF$		-	5.6	12.3	1.0	14	1.0	15.5	ns
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$									
		C _L = 15 pF		-	3.0	5.9	1.0	7.0	1.0	7.5	ns
		$C_L = 50 pF$			4.2	7.9	1.0	9.0	1.0	10.0	ns
C_{PD}	power dissipation capacitance	$C_L = 50 \text{ pF}; f_i = 1 \text{ MHz};$ $V_I = \text{GND to } V_{CC}$	[3]	-	10.0	-	-	-	-	-	pF
For type	74AHCT08										
t _{pd}	propagation	nA, nB to nY; see Figure 6	[2]								
	delay	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$									
		$C_L = 15 pF$		-	3.2	6.9	1.0	8.0	1.0	9.0	ns
		$C_L = 50 pF$		-	4.2	7.9	1.0	9.0	1.0	10.0	ns
C_{PD}	power dissipation capacitance	$C_L = 50 \text{ pF}; f_i = 1 \text{ MHz};$ $V_I = \text{GND to } V_{CC}$	[3]	-	12.0	-	-	-	-	-	pF

^[1] Typical values are measured at nominal supply voltage (V_{CC} = 3.3 V and V_{CC} = 5.0 V).

 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma (C_L \times V_{CC}^2 \times f_o) \text{ where:}$

 f_i = input frequency in MHz, f_o = output frequency in MHz

 C_L = output load capacitance in pF

 V_{CC} = supply voltage in Volts

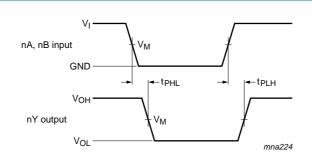
N = number of inputs switching

 $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

^[2] t_{pd} is the same as t_{PLH} and t_{PHL} .

^[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

11. Waveforms



Measurement points are given in Table 8.

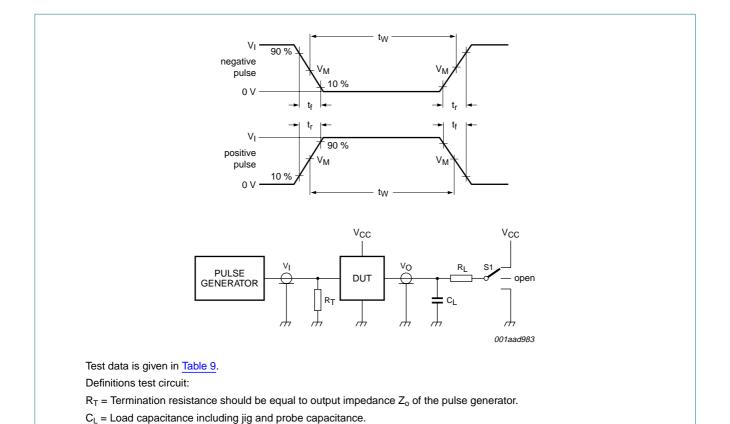
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. The input (nA, nB) to output (nY) propagation delays

Table 8. Measurement points

Туре	Input	Output
	V _M	V _M
74AHC08	0.5V _{CC}	0.5V _{CC}
74AHCT08	1.5 V	0.5V _{CC}

8 of 14



S1 = Test selection switch.

Fig 7. Load circuit for switching times

R_L = Load resistance.

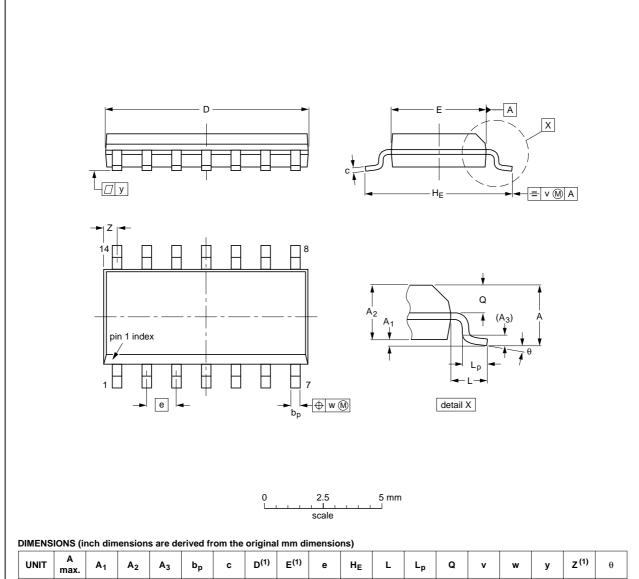
Table 9. Test data

Туре	Input		Load		S1 position				
	VI	t _r , t _f	CL	R _L	t _{PHL} , t _{PLH}	t _{PZH} , t _{PHZ}	t _{PZL} , t _{PLZ}		
74AHC08	V_{CC}	\leq 3.0 ns	15 pF, 50 pF	1 kΩ	open	GND	V _{CC}		
74AHCT08	3.0 V	≤ 3.0 ns	15 pF, 50 pF	1 kΩ	open	GND	V _{CC}		

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075	0.35 0.34	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	0°

Note

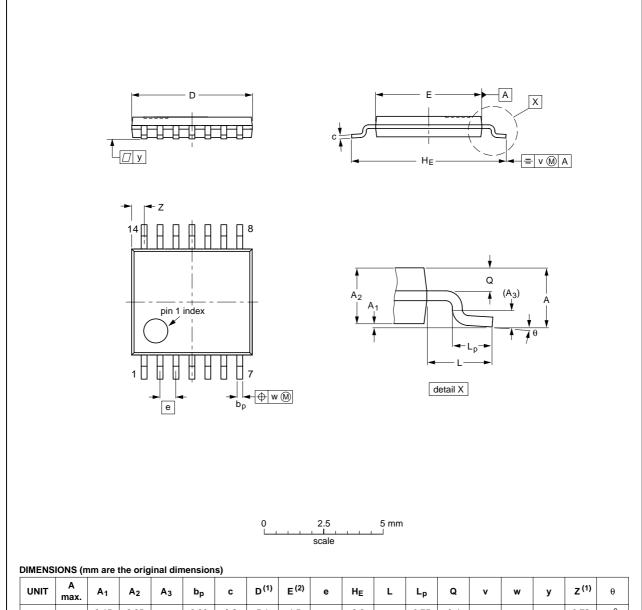
1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

	REFER	EUROPEAN	ISSUE DATE		
IEC	JEDEC	JEITA		PROJECTION	1330E DATE
076E06	MS-012				99-12-27 03-02-19
	_	IEC JEDEC		IEC JEDEC JEITA	IEC JEDEC JEITA PROJECTION

Fig 8. Package outline SOT108-1 (SO14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1



UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ	
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°	

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ICCUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT402-1		MO-153				99-12-27 03-02-18	

Fig 9. Package outline SOT402-1 (TSSOP14)

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DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm SOT762-1

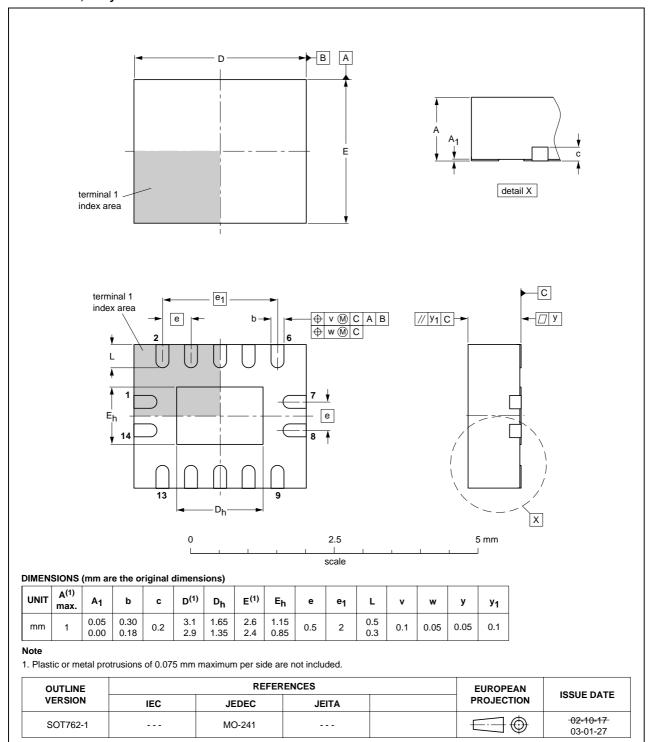


Fig 10. Package outline SOT762-1 (DHVQFN14)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
LSTTL	Low-power Schottky Transistor-Transistor Logic
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
CDM	Charged Device Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

	· · · · · · · · · · · · · · · · · · ·			
Document ID	Release date	Data sheet status	Change notice	Supersedes
74AHC_AHCT08_3	20071114	Product data sheet	-	74AHC_AHCT08_2
Modifications:	 The format of this of NXP Semicondu 	data sheet has been rede uctors.	esigned to comply with the	e new identity guidelines
	 Legal texts have be 	een adapted to the new c	ompany name where app	propriate.
	 Section 3: DHVQF 	N14 package added.		
	 Section 7: derating 	values added for DHVQI	FN14 package.	
	 Section 12: outline 	drawing added for DHVC	QFN14 package.	
74AHC_AHCT08_2	19990924	Product specification	-	74AHC_AHCT08_1
74AHC_AHCT08_1	19981218	Product specification	-	-

15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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